

# SOT462-1

plastic rectangular-DIL-bent-SIL (reverse bent) power package; 13 leads

8 February 2016

Package information

## 1. Package summary

<b>Terminal position code</b>	Z (zig-zag)
<b>Package type descriptive code</b>	RDBS13P
<b>Package type industry code</b>	RDBS13P
<b>Package style descriptive code</b>	RDBS (right-angle DIL-bent-SIL)
<b>Package style suffix code</b>	P (power)
<b>Package body material type</b>	P (plastic)
<b>Mounting method type</b>	T (through-hole mount)
<b>Issue date</b>	12-3-2003

Table 1. Package summary

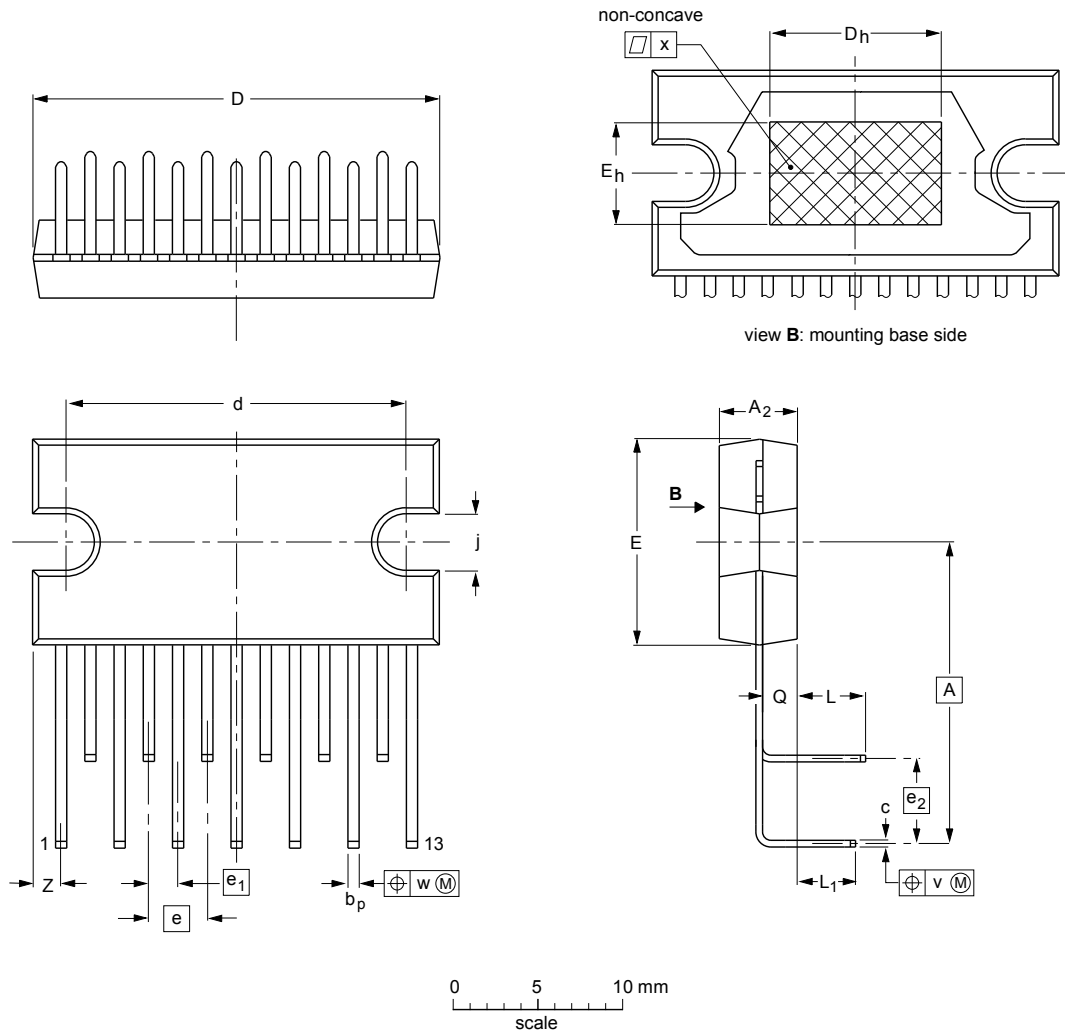
Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	23.6	-	23.8	24	mm
E	package width	11.8	-	12	12.2	mm
A	seated height	[tbd]	-	17.7	[tbd]	mm
A <sub>2</sub>	package height	4.4	-	4.5	4.6	mm
n <sub>2</sub>	actual quantity of termination	-	-	13	-	



2. Package outline

RDBS13P: plastic rectangular-DIL-bent-SIL (reverse bent) power package; 13 leads

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DIMENSIONS (mm are the original dimensions)

UNIT	A	A <sub>2</sub>	b <sub>p</sub>	c	D <sup>(1)</sup>	d	D <sub>h</sub>	E <sup>(1)</sup>	e	e <sub>1</sub>	e <sub>2</sub>	E <sub>h</sub>	j	L	L <sub>1</sub>	Q	v	w	x	Z <sup>(1)</sup>
mm	17.7	4.6 4.4	0.75 0.60	0.48 0.38	24.0 23.6	20.0 19.6	10	12.2 11.8	3.4	1.7	5.08	6	3.4 3.1	4.25 3.75	3.65 3.15	2.1 1.9	0.6	0.4	0.03	2.00 1.45

Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT462-1						-00-03-02- 03-03-12

Fig. 1. Package outline RDBS13P (SOT462-1)

### 3. Legal information

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